PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company	STMicroelectronics International N.V	
1.2 PCN No.	MDG/16/9518	
1.3 Title of PCN	Change leadframe supplier location and molding compound - STM8AFx VFQFPN 32 5x5 automotive selected products	
1.4 Product Category	Selected STM8AFx automotive products in VFQFPN 32 5x5 package	
1.5 Issue date	2016-07-28	

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	SETTLES JEFF	
2.1.2 Phone	+44 1628896222	
2.1.3 Email	jeff.settles@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Michel BUFFA	
2.1.2 Marketing Manager	Daniel COLONNA	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), lead frame, resin, wire,)	Amkor ATP3 (Philippines)

4. Description of change		
	Old	New
4.1 Description	Change from: - previous leadframe supplier location : LGI (Fuzhou, China) - previous molding compound : Sumitomo EME-G700	Change to: - new leadframe supplier location : ALS (Ansan, Korea) - new molding compound : Sumitomo EME- G700Y See more information in PCN9518_Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change		
	LGI leadframe supplier stops its activity in China, due to Chinese government decision. Consequently leadframe supplier changes from LGI (Fuzhou, China) to ALS (Ansan, Korea). Moreover, ST Microcontrollers Division takes the opportunity of this decision to improve Bill Of	
	Material by changing the molding compound.	
5.2 Customer Benefit	SERVICE CONTINUITY	

6. Marking of parts / traceability of change	
6.1 Description	Traceability of the change is ensured by ST internal tools.

7. Timing / schedule	
7.1 Date of qualification results	2016-07-28
7.2 Intended start of delivery	2017-01-28
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description PCN9518_MDG-MCD RER1517 reliability evaluation report.pdf			
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2016-07-28

9. Attachments (ad	ditional documentations)
9518PpPrdtLst.pdf PCN9518_Additional information.pdf	
PCN9518 MDG-MCD RFR1517 reliability evaluation report ndf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No 10.1.2 Supplier Part No		10.1.2 Supplier Part No
	STM8AF6266UCY	

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